ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES	C. Bannockt	ourn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the s encompass	ubstances es all lowe	within the r er level mate	manufacture erials for wh	er listed iter ich the mar	n. Note: nufacture	if the item is an as r has engineering	sembly with lowe responsibility.
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials an					ls and Mfg	and Mfg Information			
Supplier Information														
Company name* Com			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2025-09-17			
Contact Name	ontact Name Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewards Product			luct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - R			- Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Iten		n Number Mfr Item Name			Effective Dat	Date Version Manufacturing Site		ing Site	W	eight*	UOM	Unit Type	
	NSBC11	NSBC114YPDP6T5G SOT-963 COM		NBRT/PBRT TR		2025-09-17			CN1		1.1	9	mg	Each
Manufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Ma	lating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperatu		ure Max Time at Peak Temper		Гетрегаtur	mperature Number of Reflow Cycles		eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		seconds	3		
Comments														
evel 1 - maximum time at peak temperatu	re during sol	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.03	mg	
Lead Frame	0.52	mg	Supplier	Silver (Ag)	7440-22-4		0.0473	mg	
			В	Nickel (Ni)	7440-02-0		0.1914	mg	
			Supplier	Iron (Fe)	7439-89-6		0.2626	mg	
			Supplier	Copper (Cu)	7440-50-8		0.0187	mg	
Mold Compound-Black	0.61	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.061	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.003	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0884	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.3965	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.061	mg	
Plating	0.02	mg	Supplier	Tin (Sn)	7440-31-5		0.02	mg	
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg	